

Fabrication drawing for COLUTAV3_tester board
 Board version: 1.0
 Material FR4
 Board thickness- 0.068" +10%-10%
 Finish - immersion gold
 Use tolerance of ± 0.010 " for hole-to-edge dimensions.
 Thieving allowed
 Vias have drill diameter of 10mils. All other holes are component holes.
 The drill diameters for component holes are finished hole diameters
 Exposed paddle on the underside of 20 chips.
 vias should be solder filled or plugged.
 For special treatment of QFN100 socket see file socket.doc

Proposed stack-up :

Layer	Material	Thickness	Weight
top layer	prepreg	4 mils	1.2 mils
layer 2	laminite	10 mils	1.2 mils
layer 3	prepreg	10 mils	1.2 mils
layer 4	laminite	10 mils	1.2 mils
layer 5	prepreg	10 mils	1.2 mils
layer 6	laminite	10 mils	1.2 mils
layer 7	prepreg	4 mils	1.2 mils
bottom layer	prepreg	4 mils	1.2 mils

